

# Interference Search

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	0	(building contacting dicing separating wafer (invar or alloy) film).clm.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:39
L4	0	(buliding contacting dicing separating wafer (invar or alloy) film pushing).clm.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:39
L5	1	(contacting metal film dicing wafer (invar or alloy) film).clm.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:39
L6	0	(contacting metal film dicing expansion (invar or alloy) film).clm.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:39
L7	4	(metal film dicing expansion (invar or alloy) film).clm.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:40
L10	2	(metal dicing film expansion semiconductor linear film).clm.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:41
L11	0	(expansion coefficient separating semiconductor linear (invar or alloy with "42")).clm.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:41
L12	6	(expansion coefficient semiconductor linear (invar or alloy with "42")).clm. and 324/754.ccls.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:42

L13	0	(expansion coefficient semiconductor linear dicing separating wafer).clm. and 324/754.ccls.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:42
L14	0	(expansion probe linear dicing separating wafer). clm. and 324/754. ccls.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:42
L15	1	(expansion probe dic\$3 separat\$3 wafer). clm. and 324/754. ccls.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:42
L16	0	(invar probe dic\$4 separat\$3 wafer). clm. and 324/754. ccls.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:43
L17	1	(invar probe separat \$3 wafer).clm. and 324/754.ccls.	US- PGPUB; USPAT	AND	ON	2008/04/23 10:43

4/23/2008 10:44:06 AM

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